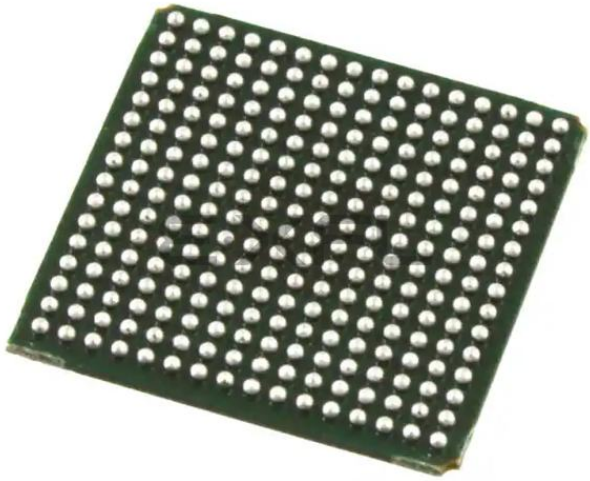

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	2704
Total RAM Bits	113664
Number of I/O	160
Number of Gates	210000
Voltage - Supply	2.3V ~ 3.6V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 105°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfx200eb-03f256i

Product Line	Ordering Part Number	Product Status	Reference PCN
LFX500B	LFX500B-03F516C	**Discontinued**	PCN#09-10
	LFX500B-04F516C		
	LFX500B-05F516C		
	LFX500B-03F900C		
	LFX500B-03FN900C		
	LFX500B-04F900C		
	LFX500B-04FN900C		
	LFX500B-05F900C		
	LFX500B-05FN900C		
LFX500C	LFX500C-03F516C	**Discontinued**	PCN#09-10
	LFX500C-04F516C		
	LFX500C-03F900C		
	LFX500C-03FN900C		
	LFX500C-04F900C		
	LFX500C-04FN900C		
LFX1200B	LFX1200B-03FE680C	**Discontinued**	PCN#03A-10
	LFX1200B-04FE680C		
	LFX1200B-05FE680C		
	LFX1200B-03F900C		
	LFX1200B-04F900C		
	LFX1200B-05F900C		
LFX1200C	LFX1200C-03FE680C	**Discontinued**	PCN#03A-10
	LFX1200C-04FE680C		
	LFX1200C-03F900C		
	LFX1200C-04F900C		
LFX125EB	LFX125EB-03F256C	Active / Orderable	
	LFX125EB-03FN256C		
	LFX125EB-04F256C		
	LFX125EB-04FN256C		
	LFX125EB-05F256C		
	LFX125EB-05FN256C		
	LFX125EB-03F256I		
	LFX125EB-03FN256I		
	LFX125EB-04F256I		
	LFX125EB-04FN256I		
	LFX125EB-03F516C	**Discontinued**	PCN#09-10
	LFX125EB-04F516C		
	LFX125EB-05F516C		
	LFX125EB-03F516I		
	LFX125EB-04F516I		
LFX125EC	LFX125EC-03F256C	**Discontinued**	PCN#09-10
	LFX125EC-03FN256C		
	LFX125EC-04F256C		
	LFX125EC-04FN256C		
	LFX125EC-03F256I		
	LFX125EC-03FN256I		

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Internet: http://www.latticesemi.com

Product Line	Ordering Part Number	Product Status	Reference PCN
LFX500EC (Cont'd)	LFX500EC-03F900C	**Discontinued**	PCN#09-10
	LFX500EC-03FN900C		
	LFX500EC-04F900C		
	LFX500EC-04FN900C		
	LFX500EC-03F900I		
	LFX500EC-03FN900I		
LFX1200EB	LFX1200EB-03FE680C	**Discontinued**	PCN#03A-10
	LFX1200EB-04FE680C		
	LFX1200EB-05FE680C		
	LFX1200EB-03FE680I		
	LFX1200EB-04FE680I		
	LFX1200EB-03F900C		
	LFX1200EB-04F900C		
	LFX1200EB-05F900C		
	LFX1200EB-03F900I		
	LFX1200EB-04F900I		
LFX1200EC	LFX1200EC-03FE680C	**Discontinued**	PCN#03A-10
	LFX1200EC-04FE680C		
	LFX1200EC-03FE680I		
	LFX1200EC-03F900C		
	LFX1200EC-04F900C		
	LFX1200EC-03F900I		

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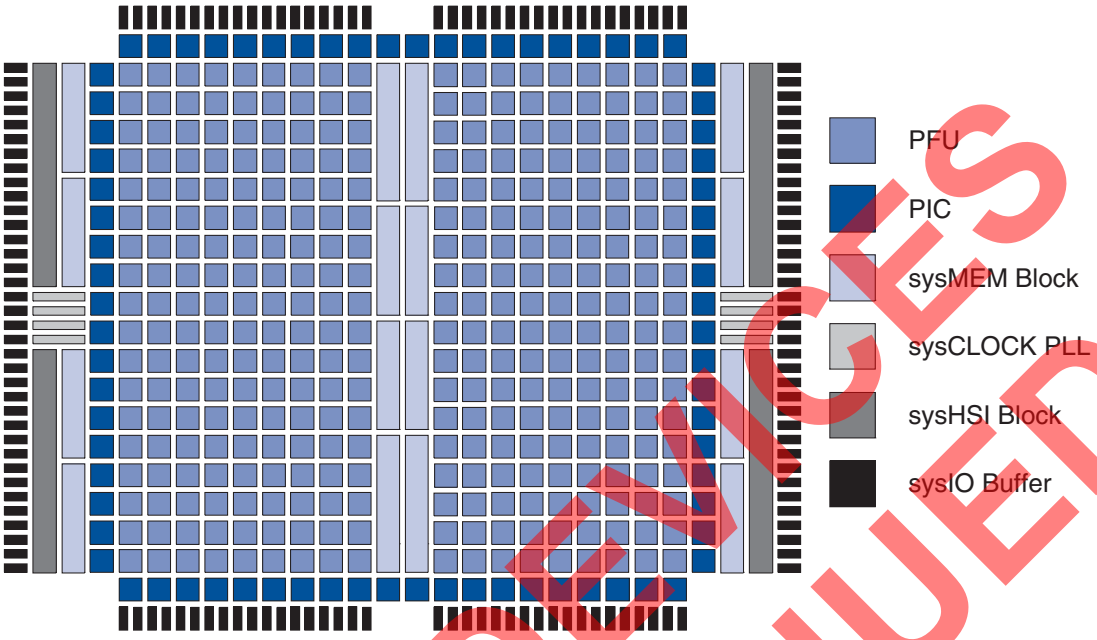
Figure 1. ispXPGA Block Diagram



Programmable Function Unit

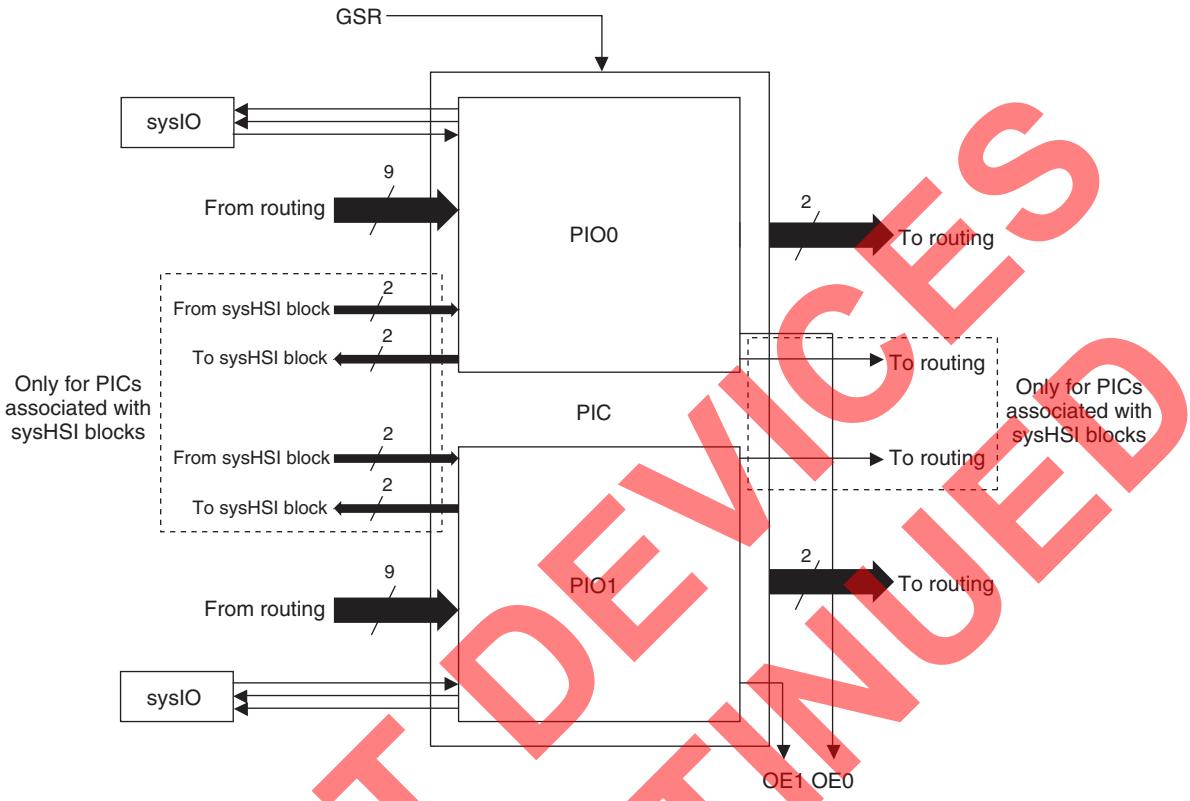
The Programmable Function Unit (PFU) is the basic building block of the ispXPGA architecture. The PFUs are arranged in rows and columns in the device with PFU (1,1) referring to (row 1, column 1). Each PFU consists of four Configurable Logic Elements (CLEs), four Configurable Sequential Elements (CSEs), and a Wide Logic Generator (WLG). By utilizing these components, the PFU can implement a variety of functions. Table 3 lists some of the function capabilities of the PFU.

There are 57 inputs to each PFU and nine outputs. The PFU uses 20 inputs for logic, and 37 inputs drive the control logic from which six control signals are derived for the PFU.

Table 3. Function Capability of ispXPGA PFU

Function	Capability
Look-up table	LUT-4, LUT-5, LUT-6
Wide logic functions	Up to 20 input logic functions
Multiplexing	2:1, 4:1, 8:1
Arithmetic logic	Dedicated carry chain and booth multiplication logic
Single-port RAM	16X1, 16X2, 16X4, 32X1, 32X2, 64X1
Double-port RAM	16X1, 16X2, 32X1
Shift register	8-bit shift registers (up to 32-bit shift capability)

Figure 10. ispXPGA PIC



Programmable Input/Output

The PIO is the building block of a PIC. The PIO has a total of 11 inputs and five outputs. Nine of the 11 inputs are generated from routing. The inputs from routing are the PIO Input (IN), Feed-Thru (FT), Clock (CLK), Input Clock Enable (ICE), Input Set/Reset (ISR), Output Clock Enable (OCEN), Output Set/Reset (OSR), PIO Output Enable (OEN), and PIO Input Enable (IEN). The remaining inputs are the sysIO input buffer signal and the Global Set/Reset signal. Three of the five outputs (OUT0, OUT1, and OE) feed routing. The last two outputs feed the sysIO buffer directly as the output and output enable of the sysIO output buffer.

PIOs associated with sysHSI blocks contain two additional inputs and outputs to support the sysHSI block. The two inputs come from the sysHSI block associated with the PIO, and the two outputs feed the sysHSI block. One of the inputs routes directly through the PIO to routing, while the other is multiplexed with the Feed-Thru, register bypass, and Q output of the register to form the OUT1 output of the PIO. The outputs to the sysHSI block are the same signals as the outputs which feed the sysIO buffers (sysIO Output and sysIO Output Enable).

Each PIO has an input register, an output register, and an output enable register as shown in Figure 11. The input register path of the PIO has a 'delay' option, which slows the data-flow. A two-input OR function of the Global Set/Reset (GSR) and Set/Reset (ISR or OSR) signals creates the set/reset term for the respective registers. Each PIO has two pairs of set/reset and clock enable signals. One is exclusive to the input register, whereas the other is common for both the output and output enable registers. The clock (CLK) is common to all registers in a PIO, and the polarity of the clock is controllable. The input, output, and the output enable registers can be configured as a latch or D-type flip-flop. Each PIO is capable of generating an output enable signal, which in turn becomes a PIC output.

Memory

The ispXPGA architecture provides a large amount of resources for memory intensive applications. Embedded Block RAMs (EBRs) are available to complement the Distributed Memory that is configured in the PFUs (see Look-Up Table -Distributed Memory Mode in the PFU section above). Each memory element can be configured as RAM or ROM. Additionally, the internal logic of the device can be used to configure the memory elements as FIFO and other storage types. These EBRs are referred to as sysMEM blocks. Refer to Table 1 for memory resources per device.

sysMEM Blocks

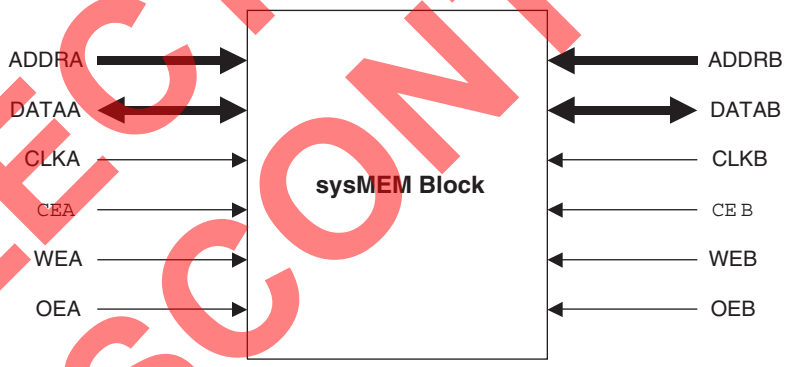
The sysMEM blocks are organized in columns distributed throughout the device. Each EBR contains 4.6K bits of dual-port RAM with dedicated control, address, and data lines for each port. Each column of sysMEM blocks has dedicated address and control lines that can be used by each block separately or cascaded to form larger memory elements. The memory cells are symmetrical and contain two sets of identical control signals. Each port has a read/write clock, clock enable, write enable, and output enable. Figure 12 illustrates the sysMEM block.

The ispXPGA memory block can operate as single-port or dual-port RAM. Supported configurations are:

- 512 x 9 bits single-port (8 bits data / 1 bit parity)
- 256 x 18 bits single-port (16 bits data / 2 bits parity)
- 512 x 9 bits dual-port (8 bits data / 1 bit parity)
- 256 x18 bits dual-port (16 bits data / 2 bits parity)

The data widths of “9” and “18” are ideal for applications where parity is necessary. This allows 9 data bits, 8 data bits plus a parity bit, 18 data bits, or 16 data bits plus two parity bits. The logic for generating and checking the parity must be customized separately.

Figure 12. sysMEM Block Diagram

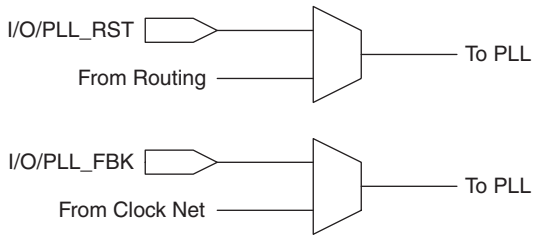


Read and Write Operations

The ispXPGA EBR has fully synchronous read and write operations as well as an asynchronous read operation. These operations allow several different types of memory to be implemented in the device.

Synchronous Read: The Clock Enable ($\overline{CE}$) and Write Enable (WE) signals control the synchronous read operation. When the $\overline{CE}$ signal is low, the clock is enabled. When the WE signal is low the read operation begins. Once the address (ADDR) is present, a rising clock edge (or falling edge depending on polarity) causes the stored data to be available on the DATA port. Figure 13 illustrates the synchronous read timing.

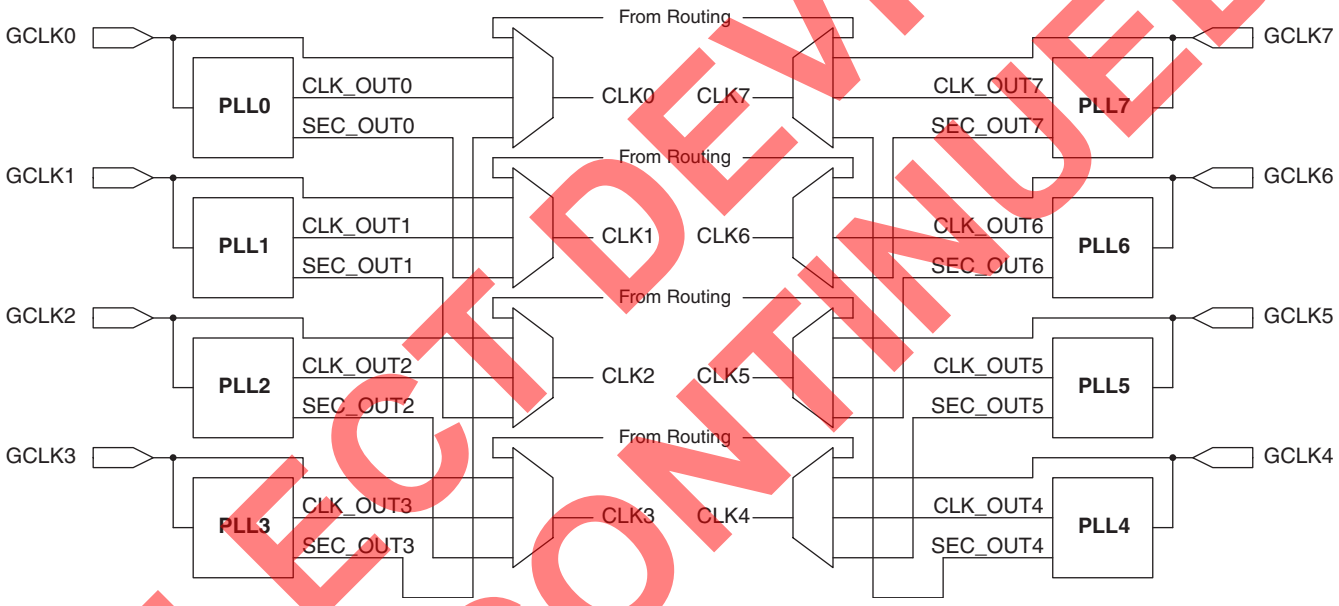
Figure 17. ispXPGA PLL_RST and PLL_FBK Generation



Clock Routing

The Global Clock Lines (GCLK) have two sources, their dedicated pins and the sysCLOCK circuit. Figure 18 illustrates the generation of the Global Clock Lines.

Figure 18. Global Clock Line Generation



sysIO Capability

All the ispXPGA devices have eight sysIO banks, where each bank is capable of supporting multiple I/O standards. Each sysIO bank has its own I/O supply voltage (V_{CCO}) and reference voltage (V_{REF}) resources allowing each bank complete independence from the others. Each I/O is individually configurable based on the bank's V_{CCO} and V_{REF} settings. In addition, each I/O has configurable drive strength, weak pull-up, weak pull-down, or a bus-keeper latch. Table 4 lists the number of I/Os supported per bank in each of the ispXPGA devices. In addition, 5V tolerant inputs are specified within an I/O bank that is connected to V_{CCO} of 3.0V to 3.6V for LVCMOS 3.3, LVTTL and PCI interfaces.

Table 5 lists the sysIO standards with the typical values for V_{CCO}, V_{REF} and V_{TT}.

The TOE, JTAG TAP pins, PROGRAM, CFG0 and DONE pins of the ispXPGA device are the only pins that do not have the sysIO capabilities. The TOE and CFG0 pins operate off the V_{CC} of the device, supporting only the LVCMOS standard corresponding to the device supply voltage. The TAP pins have a separate supply voltage (V_{CCJ}), which determines the LVCMOS standard corresponding to that supply voltage.

There are three classes of I/O interface standards that are implemented in the ispXPGA devices. The first is the unterminated, single-ended interface. It includes the 3.3V LVTTL standard along with the 1.8V, 2.5V, and 3.3V LVCMOS interface standards. Additionally, PCI and AGP-1X are subsets of this type of interface.

High Speed Serial Interface Block (sysHSI Block)[1]

The High Speed Serial Interface (sysHSI) allows high speed serial data transfer over a pair of LVDS I/O. The ispXPGA devices have multiple sysHSI blocks.

Each sysHSI block has two SERDES blocks which contain two main sub-blocks, Transmitter (with a serializer) and Receiver (with a deserializer) including Clock/Data Recovery Circuit (CDR). Each SERDES can be used as a full duplex channel. The two SERDES in sysHSI blocks share a common clock and must operate at the same nominal frequency. Figure 20 shows the sysHSI block.

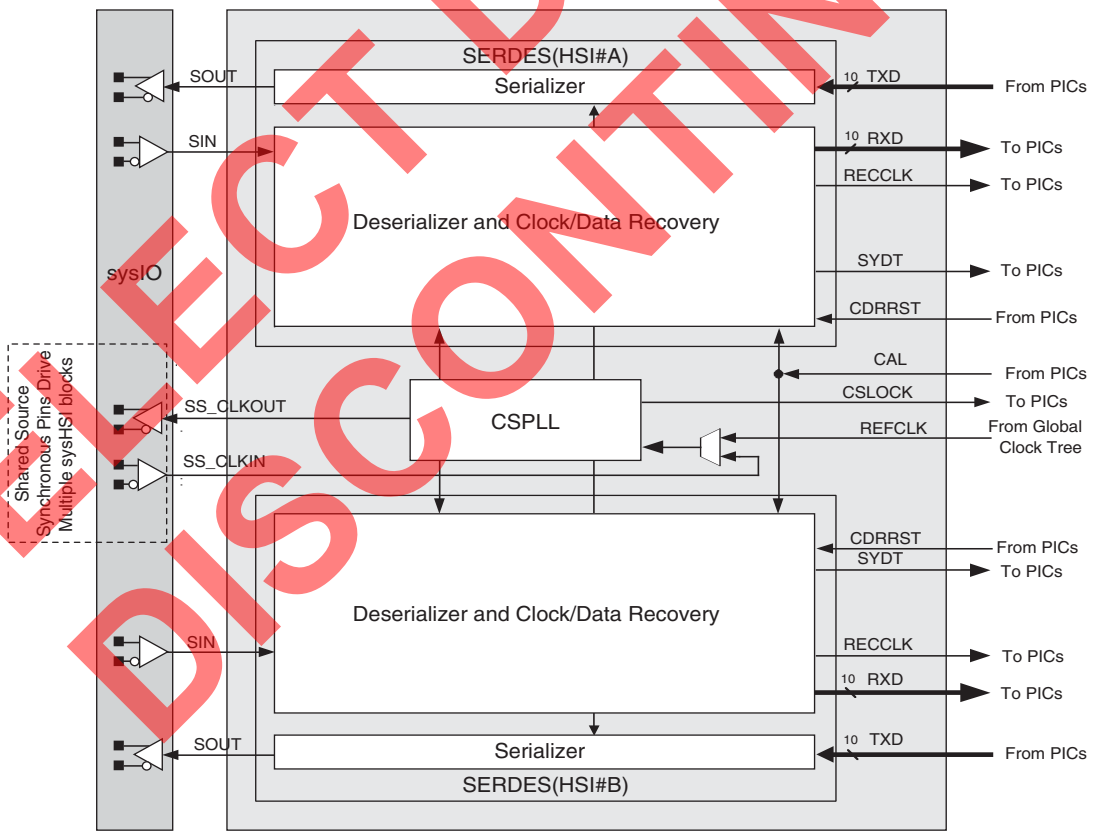
Device features support two data coding modes: 10B/12B and 8B/10B (for use with other encoding schemes, see Lattice's sysHSI technical notes). The encoding and decoding of the 10B/12B standard are performed within the sysHSI block. For the 8B/10B standard, the symbol boundaries are aligned internally but the encoding and decoding are performed outside the sysHSI block.

Each SERDES block receives a single high speed serial data input stream (with embedded clock) from an input, and provide a low speed 10-bit wide data stream and a recovered clock to the device. For transmitting, SERDES converts a 10-bit wide low-speed data stream to a single high-speed data stream with embedded clock for output.

Additionally, multiple sysHSI blocks can be grouped together to form a source synchronous interface of 1-10 channels.

For more information on the SERDES/CDR, refer to TN1020, sysHSI Usage Guidelines.

Figure 20. sysHSI Block Diagram



1. "E-Series" does not support sysHSI.

Absolute Maximum Ratings[1, 2, 3]

	1.8V	2.5V/3.3V
Supply Voltage (V_{CC})	-0.5 to 2.5V	-0.5 to 5.5V
PLL Supply Voltage (V_{CCP})	-0.5 to 2.5V	-0.5 to 5.5V
Output Supply Voltage (V_{CCO})	-0.5 to 4.5V	-0.5 to 4.5V
IEEE 1149.1 TAP Supply Voltage (V_{CCJ})	-0.5 to 4.5V	-0.5 to 4.5V
Input Voltage Applied[4, 5]	-0.5 to 5.5V	-0.5 to 5.5V
Storage Temperature	-65 to 150°C	-65 to 150°C
Junction Temperature (T_J) with Power Applied	-55 to 150°C	-55 to 150°C

1. Stress above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied (while programming, following the programming specifications).
2. Compliance with the Lattice Thermal Management document is required.
3. All voltages referenced to GND.
4. Overshoot and undershoot of -2V to (V_{IH} (MAX) + 2) volts not to exceed 6V is permitted for a duration of <20ns.
5. A maximum of 64 I/Os per device with V_{IN} > 3.6V is allowed.

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V_{CC}	Supply Voltage for 1.8V device[1]	1.65	1.95	V
	Supply Voltage for 2.5V device	2.3	2.7	V
	Supply Voltage for 3.3V device	3.0	3.6	V
V_{CCP}	Supply Voltage for PLL and sysHSI blocks, 1.8V devices[1]	1.65	1.95	V
	Supply Voltage for PLL and sysHSI blocks, 2.5V devices	2.3	2.7	V
	Supply Voltage for PLL and sysHSI blocks, 3.3V devices	3.0	3.6	V
V_{CCJ}	Supply Voltage for IEEE 1149.1 Test Access Port for LVCMOS 1.8V	1.65	1.95	V
	Supply Voltage for IEEE 1149.1 Test Access Port for LVCMOS 2.5V	2.3	2.7	V
	Supply Voltage for IEEE 1149.1 Test Access Port for LVCMOS 3.3V	3.0	3.6	V
T_J (COM)	Junction Temperature Commercial Operation	0	85	C
T_J (IND)	Junction Temperature Industrial Operation	-40	105	C

1. sysHSI specification is valid for V_{CC} and V_{CCP} = 1.7V to 1.9V.

E²CMOS Erase Reprogram Specifications

Parameter	Min	Max	Units
Erase/Reprogram Cycle[1]	1,000	—	Cycles

1. Valid over commercial temperature range.

Hot Socketing Characteristics[1, 2, 3, 4]

Symbol	Parameter	Condition	Min	Typ	Max	Units
I_{DK}	Input or Tristated I/O Leakage Current	0 ð V_{IN} ð 3.0V	—	+/-50	+/-800	µA

1. Insensitive to sequence of V_{CC} and V_{CCO} when V_{CCO} ð 1.0V. For V_{CCO} > 1.0V, V_{CC} min must be present. However, assumes monotonic rise/fall rates for V_{CC} and V_{CCO}, provided (V_{IN} - V_{CCO}) ð 3.6V.
2. LVTTL, LVCMOS only.
3. 0 < V_{CC} ð V_{CC} (MAX), 0 < V_{CCO} ð V_{CCO} (MAX).
4. I_{DK} is additive to I_{PU}, I_{PD} or I_{BH}. Device defaults to pull-up until non-volatile cells are active.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min	Typ	Max	Units
I_{IL}, I_{IH}[1]	Input or I/O Low Leakage	0 ð V_{IN} < (V_{CCO} - 0.2V)	—	—	10	µA
		(V_{CCO} - 0.2V) ð V_{IN} ð 3.6V	—	—	300	µA
I_{IH}[2]	Input High Leakage Current	3.6V < V_{IN} ð 5.5V and 3.0V ð V_{CCO} ð 3.6V	—	—	3	mA
I_{PU}	I/O Active Pull-up Current	0 ð V_{IN} ð 0.7 V_{CCO}	-30	—	-150	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) ð V_{IN} ð V_{IH} (MAX)	30	—	150	µA
I_{BHLS}	Bus Hold Low Sustaining Current	V_{IN} = V_{IL} (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	V_{IN} = 0.7 V_{CCO}	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	0 ð V_{IN} ð V_{IH} (MAX)	—	—	150	µA
I_{BHHO}	Bus Hold High Overdrive Current	0 ð V_{IN} ð V_{IH} (MAX)	—	—	-150	µA
V_{BHT}	Bus Hold Trip Points		V_{CCO} * 0.35	—	V_{CCO} * 0.65	V
C_1	I/O Capacitance[3]	V_{CCO} = 3.3V, 2.5V, 1.8V	—	8	—	pf
		V_{CC} = 1.8V, V_{IO} = 0 to V_{IH} (MAX)	—		—	
C_2	Clock Capacitance[3]	V_{CCO} = 3.3V, 2.5V, 1.8V	—	8	—	pf
		V_{CC} = 1.8V, V_{IO} = 0 to V_{IH} (MAX)	—		—	
C_3	Global Input Capacitance[3]	V_{CCO} = 3.3V, 2.5V, 1.8V	—	6	—	pf
		V_{CC} = 1.8V, V_{IO} = 0 to V_{IH} (MAX)	—		—	

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. 5V tolerant inputs and I/Os should be placed in banks where 3.0V ð V_{CCO} ð 3.6V. The JTAG and sysCONFIG ports are not included for the 5V tolerant interface.
3. T_A = 25°C, f = 1.0MHz.

ispXPGA 125B/C & ispXPGA 125EB/EC Timing Adders (Cont.)

Parameter	Description	Base Parameter	-5[1]		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
LVCMOS_33_4mA_out	Using 3.3V CMOS Standard, 4mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
LVCMOS_33_5.33mA_out	Using 3.3V CMOS Standard, 5.33mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
LVCMOS_33_8mA_out	Using 3.3V CMOS Standard, 8mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.7	—	0.7	—	0.7	ns
LVCMOS_33_12mA_out	Using 3.3V CMOS Standard, 12mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
LVCMOS_33_16mA_out	Using 3.3V CMOS Standard, 16mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
LVCMOS_33_24mA_out	Using 3.3V CMOS Standard, 24mA Drive	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
AGP_1X_out	Using AGP 1x Standard	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
CTT25_out	Using CTT 2.5V	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
CTT33_out	Using CTT 3.3V	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
GTL+_out	Using GTL+	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
HSTL_I_out	Using HSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
HSTL_III_out	Using HSTL 2.5V, Class III	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
LVDS_out	Using Low Voltage Differential Signaling (LVDS)	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
BLVDS_out	Using Bus Low Voltage Differential Signaling (BLVDS)	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
LVPECL_out	Using Low Voltage PECL	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	1.0	—	1.0	—	1.0	ns
PCI_out	Using PCI Standard	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL2_I_out	Using SSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL2_II_out	Using SSTL 2.5V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL3_I_out	Using SSTL 3.3V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns
SSTL3_II_out	Using SSTL 3.3V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	ns

1. Only available for ispXPGA 125B and ispXPGA 125EB (2.5V/3.3V) devices.

Timing v.0.3

ispXPGA 200B/C & ispXPGA 200EB/EC PFU Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-5[1]		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Functional Delays								
LUTs								
t_{LUT4}	4-Input LUT Delay	—	0.41	—	0.44	—	0.51	ns
t_{LUT5}	5-Input LUT Delay	—	0.73	—	0.79	—	0.91	ns
t_{LUT6}	6-Input LUT Delay	—	0.86	—	0.93	—	1.07	ns
Shift Register (LUT)								
t_{LSR_S}	Shift Register Setup Time	-0.64	—	-0.62	—	-0.53	—	ns
t_{LSR_H}	Shift Register Hold Time	0.61	—	0.63	—	0.72	—	ns
t_{LSR_CO}	Shift Register Clock to Output Delay	—	0.70	—	0.75	—	0.86	ns
Arithmetic Functions								
$t_{LCTHRUR}$	MC (Macro Cell) Carry In to MC Carry Out Delay (Ripple)	—	0.08	—	0.09	—	0.10	ns
$t_{LCTHRUL}$[2]	MC Carry In to MC Carry Out Delay (Look Ahead)	—	0.05	—	0.05	—	0.06	ns
t_{LSTHRU}	MC Sum In to MC Sum Out Delay	—	0.42	—	0.45	—	0.52	ns
$t_{LSINCOUT}$	MC Sum In to MC Carry Out Delay	—	0.29	—	0.31	—	0.36	ns
$t_{LCINSOUTR}$	MC Carry In to MC Sum Out Delay (Ripple)	—	0.36	—	0.39	—	0.45	ns
$t_{LCINSOUTL}$	MC Carry In to MC Sum Out Delay (Look Ahead)	—	0.26	—	0.28	—	0.32	ns
Feed-thru								
t_{LFT}	PFU Feed-Thru Delay	—	0.15	—	0.16	—	0.18	ns
Distributed RAM								
t_{LRAM_CO}	Clock to RAM Output	—	1.24	—	1.33	—	1.53	ns
t_{LRAMAD_S}	Address Setup Time	-0.41	—	-0.40	—	-0.34	—	ns
t_{LRAMD_S}	Data Setup Time	0.21	—	0.22	—	0.25	—	ns
t_{LRAMWE_S}	Write Enable Setup Time	0.45	—	0.46	—	0.53	—	ns
t_{LRAMAD_H}	Address Hold Time	0.58	—	0.60	—	0.69	—	ns
t_{LRAMD_H}	Data Hold Time	0.11	—	0.11	—	0.13	—	ns
t_{LRAMWE_H}	Write Enable Hold Time	0.12	—	0.12	—	0.14	—	ns
$t_{LRAMCPW}$	Clock Pulse Width (High or Low)	2.91	—	3.00	—	3.45	—	ns
$t_{LRAMADO}$	Address to Output Delay	—	0.86	—	0.93	—	1.07	ns
Register/Latch Delays								
Registers								
t_{L_CO}	Register Clock to Output Delay	—	0.58	—	0.62	—	0.71	ns
t_{L_S}	Register Setup Time (Data before Clock)	0.14	—	0.14	—	0.16	—	ns
t_{L_H}	Register Hold Time (Data after Clock)	-0.12	—	-0.12	—	-0.10	—	ns
t_{LCE_S}	Register Clock Enable Setup Time	-0.11	—	-0.11	—	-0.09	—	ns
t_{LCE_H}	Register Clock Enable Hold Time	0.11	—	0.11	—	0.13	—	ns
Latches								
t_{L_GO}	Latch Gate to Output Delay	—	0.09	—	0.10	—	0.12	ns
t_{LL_S}	Latch Setup Time	0.14	—	0.14	—	0.16	—	ns
t_{LL_H}	Latch Hold Time	-0.12	—	-0.12	—	-0.10	—	ns
t_{LLPD}	Latch Propagation Delay (Transparent Mode)	—	0.09	—	0.10	—	0.12	ns

ispXPGA 500B/C & ispXPGA 500EB/EC PFU Timing Parameters

Over Recommended Operating Conditions

Parameter	Description	-5[1]		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
Functional Delays								
LUTs								
t_{LUT4}	4-Input LUT Delay	—	0.41	—	0.44	—	0.51	ns
t_{LUT5}	5-Input LUT Delay	—	0.73	—	0.79	—	0.91	ns
t_{LUT6}	6-Input LUT Delay	—	0.86	—	0.93	—	1.07	ns
Shift Register (LUT)								
t_{LSR_S}	Shift Register Setup Time	-0.64	—	-0.62	—	-0.53	—	ns
t_{LSR_H}	Shift Register Hold Time	0.61	—	0.63	—	0.72	—	ns
t_{LSR_CO}	Shift Register Clock to Output Delay	—	0.70	—	0.75	—	0.86	ns
Arithmetic Functions								
$t_{LCTHRUR}$	MC (Macro Cell) Carry In to MC Carry Out Delay (Ripple)	—	0.08	—	0.09	—	0.10	ns
$t_{LCTHRUL}$[2]	MC Carry In to MC Carry Out Delay (Look Ahead)	—	0.05	—	0.05	—	0.06	ns
t_{LSTHRU}	MC Sum In to MC Sum Out Delay	—	0.42	—	0.45	—	0.52	ns
$t_{LSINCOUT}$	MC Sum In to MC Carry Out Delay	—	0.29	—	0.31	—	0.36	ns
$t_{LCINSOUTR}$	MC Carry In to MC Sum Out Delay (Ripple)	—	0.36	—	0.39	—	0.45	ns
$t_{LCINSOUTL}$	MC Carry In to MC Sum Out Delay (Look Ahead)	—	0.26	—	0.28	—	0.32	ns
Feed-thru								
t_{LFT}	PFU Feed-Thru Delay	—	0.15	—	0.16	—	0.18	ns
Distributed RAM								
t_{LRAM_CO}	Clock to RAM Output	—	1.24	—	1.33	—	1.53	ns
t_{LRAMAD_S}	Address Setup Time	-0.41	—	-0.40	—	-0.34	—	ns
t_{LRAMD_S}	Data Setup Time	0.21	—	0.22	—	0.25	—	ns
t_{LRAMWE_S}	Write Enable Setup Time	0.45	—	0.46	—	0.53	—	ns
t_{LRAMAD_H}	Address Hold Time	0.58	—	0.60	—	0.69	—	ns
t_{LRAMD_H}	Data Hold Time	0.11	—	0.11	—	0.13	—	ns
t_{LRAMWE_H}	Write Enable Hold Time	0.12	—	0.12	—	0.14	—	ns
$t_{LRAMCPW}$	Clock Pulse Width (High or Low)	2.91	—	3.00	—	3.45	—	ns
$t_{LRAMADO}$	Address to Output Delay	—	0.86	—	0.93	—	1.07	ns
Register/Latch Delays								
Registers								
t_{L_CO}	Register Clock to Output Delay	—	0.58	—	0.62	—	0.71	ns
t_{L_S}	Register Setup Time (Data before Clock)	0.14	—	0.14	—	0.16	—	ns
t_{L_H}	Register Hold Time (Data after Clock)	-0.12	—	-0.12	—	-0.10	—	ns
t_{LCE_S}	Register Clock Enable Setup Time	-0.11	—	-0.11	—	-0.09	—	ns
t_{LCE_H}	Register Clock Enable Hold Time	0.11	—	0.11	—	0.13	—	ns
Latches								
t_{L_GO}	Latch Gate to Output Delay	—	0.09	—	0.10	—	0.12	ns
t_{LL_S}	Latch Setup Time	0.14	—	0.14	—	0.16	—	ns
t_{LL_H}	Latch Hold Time	-0.12	—	-0.12	—	-0.10	—	ns
t_{LLPD}	Latch Propagation Delay (Transparent Mode)	—	0.09	—	0.10	—	0.12	ns

ispXPGA 1200B/C & ispXPGA 1200EB/EC External Switching Characteristics

Over Recommended Operating Conditions

Parameter	Description	Conditions	-5[1]		-4		-3		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
t_{CO}	Global Clock Input to Output	PIO Output Register	—	6.6	—	7.1	—	8.2	ns
t_S	Global Clock Input Setup	PIO Input Register without input delay	-2.7	—	-2.7	—	-2.3	—	ns
t_H	Global Clock Input Hold	PIO Input Register without input delay	4.5	—	4.6	—	5.3	—	ns
t_{SINDLY}	Global Clock Input Setup	PIO Input Register with input delay	3.8	—	3.8	—	4.4	—	ns
t_{HINDLY}	Global Clock Input Hold	PIO Input Register with input delay	0.0	—	0.0	—	0.0	—	
t_{COPLL}	Global Clock Input to Output	PIO Output Register using PLL without delay	—	3.1	—	3.3	—	3.8	ns
t_{SPLL}	Global Clock Input Setup	PIO Input Register without input delay using PLL without delay	0.5	—	0.5	—	0.6	—	ns
t_{HPLL}	Global Clock Input Hold	PIO Input Register without input delay using PLL without delay	0.8	—	0.8	—	1.0	—	ns
$t_{SINDLYPLL}$	Global Clock Input Setup	PIO Input Register with input delay using PLL without delay	7.6	—	7.6	—	8.8	—	ns
$t_{HINDLYPLL}$	Global Clock Input Hold	PIO Input Register with input delay using PLL without delay	-4.1	—	-4.0	—	-3.4	—	ns

1. Only available for ispXPGA 1200B and ispXPGA 1200EB (2.5V/3.3V) devices.

Timing v.0.2

ispXPGA Power Supply and NC Connections[1]

Signal	256-Ball fpBGA[3]	516-Ball fpBGA[3]
V_{CC}	C3, C14, D4, D13, E5, E12, F6, F11, L6, L11, M5, M12, N4, N13, P3, P14	A9, A22, D4, D27, J1, J30, L11, L12, L15, L16, L19, L20, M11, M20, R11, R20, T11, T20, W11, W20, Y11, Y12, Y15, Y16, Y19, Y20, AB1, AB30, AG4, AG27, AK9, AK22
V_{CCO0}	F5, G5	F4, J4, M4, N11, P4, P11
V_{CCO1}	K5, L5	U4, U11, V11, W4, AB4, AE4
V_{CCO2}	M6, M7	Y13, Y14, AG6, AG9, AG12, AG14
V_{CCO3}	M10, M11	Y17, Y18, AG17, AG19, AG22, AG25
V_{CCO4}	K12, L12	U20, U27, V20, W27, AB27, AE27
V_{CCO5}	G12, F12	F27, J27, M27, N20, P20, P27
V_{CCO6}	E10, E11	D17, D19, D22, D25, L17, L18
V_{CCO7}	E6, E7	D6, D9, D12, D14, L13, L14
V_{CCP}	H3, J15	R4, T30
V_{CCJ}	A2	C4
GND	A1, A16, B2, B15, F7, F8, F9, F10, G6, G7, G8, G9, G10, G11, H6, H7, H8, H9, H10, H11, J6, J7, J8, J9, J10, J11, K6, K7, K8, K9, K10, K11, L7, L8, L9, L10, R2, R15, T1, T16	A1, A30, B2, B29, C3, C28, M12, M13, M14, M15, M16, M17, M18, M19, N12, N13, N14, N15, N16, N17, N18, N19, P12, P13, P14, P15, P16, P17, P18, P19, R12, R13, R14, R15, R16, R17, R18, R19, T12, T13, T14, T15, T16, T17, T18, T19, U12, U13, U14, U15, U16, U17, U18, U19, V12, V13, V14, V15, V16, V17, V18, V19, W12, W13, W14, W15, W16, W17, W18, W19, AH3, AH28, AJ2, AJ29, AK1, AK30
GND_P	H15, J4	R29, T4
NC[2]	—	**LFX125:** A10, A13, A16, A17, A24, A25, A26, A4, A5, A6, A7, AA1, AA2, AA28, AA29, AA3, AB28, AC1, AC28, AD1, AD27, AD4, AE28, AE29, AE3, AE30, AF27, AF28, AF29, AF3, AF4, AG1, AG10, AG11, AG15, AG2, AG20, AG23, AG24, AG29, AG3, AG8, AH1, AH15, AH19, AH2, AH20, AH23, AH24, AH30, AH7, AH8, AH9, AJ1, AJ12, AJ14, AJ15, AJ19, AJ20, AJ21, AJ23, AJ24, AJ25, AJ27, AJ30, AJ6, AJ7, AJ8, AK11, AK14, AK15, AK20, AK21, AK23, AK24, AK25, AK27, AK5, AK6, AK7, B10, B13, B16, B17, B18, B23, B24, B25, B5, B6, B7, C11, C13, C14, C16, C17, C22, C23, C24, C25, C6, C7, C8, D11, D16, D23, D24, D28, D29, D3, D7, D8, E30, E4, F1, F29, F30, G1, G2, G27, G28, G29, G30, H1, H2, H27, H28, H29, H30, J2, J28, J29, J3, K1, K2, K27, K28, K3, K4, L1, L2, L27, L3, L4, M1, M2, M29, M3, M30, V27, V28, V3, V4, W1, W30, Y1, Y27, Y28, Y3, Y30 **LFX200:** A26, A25, A24, A17, A10, A7, A6, A5, A4, B25, B24, B23, B17, B10, B7, B6, B5, C25, C24, C23, C22, C16, C11, C8, C7, C6, D24, D23, D16, D11, D8, D7, E30, F30, F29, F1, G30, G29, G28, G27, G2, G1, H30, H29, H28, H27, H2, H1, J29, J28, J3, J2, K28, K27, K4, K3, K2, K1, L27, L4, L3, L2, L1, M3, V28, V27, V4, V3, W30, W1, Y30, Y28, Y27, Y3, Y1, AA29, AA28, AA3, AA2, AA1, AD27, AD4, AE28, AE3, AF29, AF28, AF27, AF3, AG29, AG24, AG23, AG20, AG11, AG10, AG8, AG2, AG1, AH30, AH24, AH23, AH20, AH9, AH8, AH7, AH2, AH1, AJ30, AJ27, AJ25, AJ24, AJ23, AJ21, AJ15, AJ12, AJ8, AJ7, AJ6, AJ1, AK27, AK25, AK24, AK23, AK21, AK15, AK11, AK7, AK6, AK5

1. All grounds must be electrically connected at the board level.
2. NC pins should not be connected to any active signals, V_{CC} or GND.
3. Balls for GND, V_{CC} and V_{CCOx} are connected within the substrate to their respective common signals. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

ispXPGA Logic Signal Connections: 516-Ball fpBGA (Cont.)

516-Ball BGA Ball	LFX500			LFX200			LFX125		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
-	-	-	-	GND (Bank 0)	-	-	-	-	-
R2	GCLK0	-	LVDS Pair0P	GCLK0	-	LVDS Pair0P	GCLK0	-	LVDS Pair0P
R3	GCLK1	-	LVDS Pair0N	GCLK1	-	LVDS Pair0N	GCLK1	-	LVDS Pair0N
R4	VCCP0	-	-	VCCP0	-	-	VCCP0	-	-
T4	GNDP0	-	-	GNDP0	-	-	GNDP0	-	-
T3	GCLK2	-	LVDS Pair1P	GCLK2	-	LVDS Pair1P	GCLK2	-	LVDS Pair1P
T2	GCLK3	-	LVDS Pair1N	GCLK3	-	LVDS Pair1N	GCLK3	-	LVDS Pair1N
-	-	-	-	GND (Bank 1)	-	-	-	-	-
T1	BK1_IO0	CLK_OUT2	21P	BK1_IO0	CLK_OUT2	13P	BK1_IO0	CLK_OUT2	11P
-	GND (Bank 1)	-	-	-	-	-	-	-	-
U1	BK1_IO1	CLK_OUT3	21N	BK1_IO1	CLK_OUT3	13N	BK1_IO1	CLK_OUT3	11N
U2	BK1_IO2	SS_CLKOUT0P	22P	BK1_IO2	SS_CLKOUT0P	14P	BK1_IO2	SS_CLKOUT0P	12P
-	-	-	-	-	-	-	GND (Bank 1)	-	-
U3	BK1_IO3	SS_CLKOUT0N	22N	BK1_IO3	SS_CLKOUT0N	14N	BK1_IO3	SS_CLKOUT0N	12N
V1	BK1_IO4	PLL_FBK2	23P	BK1_IO4	PLL_FBK2	15P	BK1_IO4	PLL_FBK2	13P
V2	BK1_IO5	PLL_FBK3	23N	BK1_IO5	PLL_FBK3	15N	BK1_IO5	PLL_FBK3	13N
V3	BK1_IO6	-	24P	NC	-	-	NC	-	-
-	GND (Bank 1)	-	-	-	-	-	-	-	-
V4	BK1_IO7	-	24N	NC	-	-	NC	-	-
W1	BK1_IO8	-	25P	NC	-	-	NC	-	-
Y1	BK1_IO9	-	25N	NC	-	-	NC	-	-
W2	BK1_IO10	SS_CLKINOP	26P	BK1_IO6	SS_CLKIN0P	16P	BK1_IO6	SS_CLKIN0P	14P
-	-	-	-	GND (Bank 1)	-	-	-	-	-
W3	BK1_IO11	SS_CLKINON	26N	BK1_IO7	SS_CLKIN0N	16N	BK1_IO7	SS_CLKIN0N	14N
Y2	BK1_IO12		27P	BK1_IO8		17P	BK1_IO8	-	15P
-	-	-	-	-	-	-	GND (Bank 1)	-	-
Y4	BK1_IO13	-	27N	BK1_IO9	-	17N	BK1_IO9	-	15N
Y3	BK1_IO14	-	28P	NC	-	-	NC	-	-
-	GND (Bank 1)	-	-	-	-	-	-	-	-
AA1	BK1_IO15	-	28N	NC	-	-	NC	-	-
AA2	BK1_IO16	-	29P	NC	-	-	NC	-	-
AA3	BK1_IO17	-	29N	NC	-	-	NC	-	-
AB2	BK1_IO18	HSI2A_SOUTP	30P	BK1_IO10	HSI1A_SOUTP	18P/HSI1	BK1_IO10	-	16P
AC2	BK1_IO19	HSI2A_SOUTN	30N	BK1_IO11	HSI1A_SOUTN	18N/HSI1	BK1_IO11	-	16N
AB3	BK1_IO20	PLL_RST2	31P	BK1_IO12	PLL_RST2	19P/HSI1	BK1_IO12	PLL_RST2	17P
AA4	BK1_IO21	PLL_RST3	31N	BK1_IO13	PLL_RST3	19N/HSI1	BK1_IO13	PLL_RST3	17N
AC1	BK1_IO22	HSI2A_SINP	32P	BK1_IO14	HSI1A_SINP	20P/HSI1	NC	-	-
-	GND (Bank 1)	-	-	GND (Bank 1)	-	-	-	-	-
AD1	BK1_IO23	HSI2A_SINN	32N	BK1_IO15	HSI1A_SINN	20N/HSI1	NC	-	-
AE1	BK1_IO24	VREF1	33P/HSI2	BK1_IO16	VREF1	21P/HSI1	BK1_IO14	VREF1	18P
AF1	BK1_IO25		33N/HSI2	BK1_IO17	-	21N/HSI1	BK1_IO15	-	18N
AC3	BK1_IO26	HSI2B_SOUTP	34P/HSI2	BK1_IO18	HSI1B_SOUTP	22P/HSI1	BK1_IO16	-	19P
-	-	-	-	-	-	-	GND (Bank 1)	-	-
AC4	BK1_IO27	HSI2B_SOUTN	34N/HSI2	BK1_IO19	HSI1B_SOUTN	22N/HSI1	BK1_IO17	-	19N
AD2	BK1_IO28	-	35P/HSI2	BK1_IO20	-	23P/HSI1	BK1_IO18	-	20P
AD3	BK1_IO29	-	35N/HSI2	BK1_IO21	-	23N/HSI1	BK1_IO19	-	20N
AE2	BK1_IO30	HSI2B_SINP	36P/HSI2	BK1_IO22	HSI1B_SINP	24P/HSI1	BK1_IO20	-	21P
-	GND (Bank 1)	-	-	GND (Bank 1)	-	-	-	-	-
AF2	BK1_IO31	HSI2B_SINN	36N/HSI2	BK1_IO23	HSI1B_SINN	24N/HSI1	BK1_IO21	-	21N
AD4	BK1_IO32	-	37P/HSI2	NC	-	-	NC	-	-

ispXPGA Logic Signal Connections: 900-Ball fpBGA (Cont.)

900 fpBGA Ball	LFX1200			LFX500		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
L2	BK0_IO35	HSI1B_SINN	17N/HSI1	BK0_IO15	HSI0B_SINN	7N/HSI0
L6	BK0_IO36	-	18P/HSI1	BK0_IO16	-	8P/HSI0
L5	BK0_IO37	-	18N/HSI1	BK0_IO17	-	8N/HSI0
M1	BK0_IO38	HSI2A_SOUTP	19P/HSI1	BK0_IO18	HSI1A_SOUTP	9P/HSI1
-	-	-	-	GND (Bank 0)	-	-
M2	BK0_IO39	HSI2A_SOUTN	19N/HSI1	BK0_IO19	HSI1A_SOUTN	9N/HSI1
L3	BK0_IO40	-	20P/HSI1	BK0_IO20	-	10P/HSI1
L4	BK0_IO41	-	20N/HSI1	BK0_IO21	-	10N/HSI1
M6	BK0_IO42	HSI2A_SINP	21P/HSI2	BK0_IO22	HSI1A_SINP	11P/HSI1
-	GND (Bank 0)	-	-	-	-	-
M5	BK0_IO43	HSI2A_SINN	21N/HSI2	BK0_IO23	HSI1A_SINN	11N/HSI1
M4	BK0_IO44	-	22P/HSI2	BK0_IO24	-	12P/HSI1
M3	BK0_IO45	-	22N/HSI2	BK0_IO25	-	12N/HSI1
N1	BK0_IO46	HSI2B_SOUTP	23P/HSI2	BK0_IO26	HSI1B_SOUTP	13P/HSI1
-	-	-	-	GND (Bank 0)	-	-
N2	BK0_IO47	HSI2B_SOUTN	23N/HSI2	BK0_IO27	HSI1B_SOUTN	13N/HSI1
N7	BK0_IO48	-	24P/HSI2	BK0_IO28	-	14P/HSI1
N6	BK0_IO49	-	24N/HSI2	BK0_IO29	-	14N/HSI1
P1	BK0_IO50	HSI2B_SINP	25P/HSI2	BK0_IO30	HSI1B_SINP	15P/HSI1
-	GND (Bank 0)	-	-	-	-	-
P2	BK0_IO51	HSI2B_SINN	25N/HSI2	BK0_IO31	HSI1B_SINN	15N/HSI1
N3	BK0_IO52	-	26P/HSI2	BK0_IO32	-	16P/HSI1
N4	BK0_IO53	-	26N/HSI2	BK0_IO33	-	16N/HSI1
P6	BK0_IO54	PLL_RST0	27P/HSI2	BK0_IO38	PLL_RST0	19P
P5	BK0_IO55	PLL_RST1	27N/HSI2	BK0_IO35	PLL_RST1	17N
P3	BK0_IO56	-	28P/HSI2	BK0_IO36	-	18P
P4	BK0_IO57	-	28N/HSI2	BK0_IO39	-	19N
R7	BK0_IO58	PLL_FBK0	29P	BK0_IO34	PLL_FBK0	17P
-	GND (Bank 0)	-	-	GND (Bank 0)	-	-
R6	BK0_IO59	PLL_FBK1	29N	BK0_IO37	PLL_FBK1	18N
R1	BK0_IO60	CLK_OUT0	30P	BK0_IO40	CLK_OUT0	20P
-	-	-	-	GND (Bank 0)	-	-
R2	BK0_IO61	CLK_OUT1	30N	BK0_IO41	CLK_OUT1	20N
-	GND (Bank 0)	-	-	-	-	-
R3	GCLK0	-	LVDS Pair0P	GCLK0	-	LVDS Pair0P
R4	GCLK1	-	LVDS Pair0N	GCLK1	-	LVDS Pair0N
R5	VCCP0	-	-	VCCP0	-	-
T3	GNDP0	-	-	GNDP0	-	-
T4	GCLK2	-	LVDS Pair1P	GCLK2	-	LVDS Pair1P
T5	GCLK3	-	LVDS Pair1N	GCLK3	-	LVDS Pair1N
-	GND (Bank 1)	-	-	-	-	-
T2	BK1_IO0	CLK_OUT2	31P	BK1_IO0	CLK_OUT2	21P

ispXPGA Logic Signal Connections: 900-Ball fpBGA (Cont.)

900 fpBGA Ball	LFX1200			LFX500		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
AB1	BK1_IO35	HSI3B_SOUTN	48N/HSI3	NC	-	-
AC6	BK1_IO36	-	49P/HSI4	NC	-	-
AC5	BK1_IO37	-	49N/HSI4	NC	-	-
AC2	BK1_IO38	HSI3B_SINP	50P/HSI4	NC	-	-
AC1	BK1_IO39	HSI3B_SINN	50N/HSI4	NC	-	-
AC4	BK1_IO40	-	51P/HSI4	NC	-	-
AC3	BK1_IO41	-	51N/HSI4	NC	-	-
AD2	BK1_IO42	HSI4A_SOUTP	52P/HSI4	NC	-	-
-	GND (Bank 1)	-	-	-	-	-
AD1	BK1_IO43	HSI4A_SOUTN	52N/HSI4	NC	-	-
AD3	BK1_IO44	-	53P/HSI4	BK1_IO32	-	37P/HSI3
AD4	BK1_IO45	-	53N/HSI4	BK1_IO33	-	37N
AE2	BK1_IO46	HSI4A_SINP	54P/HSI4	BK1_IO34	-	38P
AE1	BK1_IO47	HSI4A_SINN	54N/HSI4	BK1_IO35	-	38N
AD5	BK1_IO48	-	55P/HSI4	BK1_IO25	-	33N
AD6	BK1_IO49	VREF1	55N/HSI4	BK1_IO24	VREF1	33P
AF2	BK1_IO50	HSI4B_SOUTP	56P/HSI4	BK1_IO26	HSI2B_SOUTP	34P
-	GND (Bank 1)	-	-	-	-	-
AF1	BK1_IO51	HSI4B_SOUTN	56N/HSI4	BK1_IO27	HSI2B_SOUTN	34N
AE3	BK1_IO52	-	57P	BK1_IO28	-	35P
AE4	BK1_IO53	-	57N	BK1_IO29	-	35N
AG1	BK1_IO54	HSI4B_SINP	58P	BK1_IO30	HSI2B_SINP	36P
-	-	-	-	GND (Bank 1)	-	-
AG2	BK1_IO55	HSI4B_SINN	58N	BK1_IO31	HSI2B_SINN	36N
AE5	BK1_IO56	-	59P	BK1_IO36	-	39P
AF4	BK1_IO57	-	59N	BK1_IO37	-	39N
AH1	BK1_IO58	-	60P	BK1_IO38	-	40P
-	GND (Bank 1)	-	-	GND (Bank 1)	-	-
AH2	BK1_IO59	-	60N	BK1_IO39	-	40N
AF3	BK1_IO60	-	61P	BK1_IO40	-	41P
AG3	BK1_IO61	-	61N	BK1_IO41	-	41N
AH4	TCK	-	-	TCK	-	-
AJ3	TMS	-	-	TMS	-	-
AK3	TOE	-	-	TOE	-	-
AG5	BK2_IO0	-	62P	BK2_IO0	-	42P
AH5	BK2_IO1	-	62N	BK2_IO1	-	42N
AJ4	BK2_IO2	-	63P	BK2_IO2	-	43P
-	GND (Bank 2)	-	-	GND (Bank 2)	-	-
AK4	BK2_IO3	-	63N	BK2_IO3	-	43N
AG6	BK2_IO4	-	64P	BK2_IO4	-	44P
AH6	BK2_IO5	-	64N	BK2_IO5	-	44N
AJ5	BK2_IO6	-	65P	BK2_IO6	-	45P

ispXPGA Logic Signal Connections: 900-Ball fpBGA (Cont.)

900 fpBGA Ball	LFX1200			LFX500		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
B15	BK7_IO1	-	217N	BK7_IO1	-	147N
C15	BK7_IO2	-	218P	BK7_IO2	-	148P
-	GND (Bank 7)	-	-		-	-
D15	BK7_IO3	-	218N	BK7_IO3	-	148N
E15	BK7_IO4	-	219P	BK7_IO4	-	149P
F15	BK7_IO5	-	219N	BK7_IO5	-	149N
A14	BK7_IO6	-	220P	BK7_IO6	-	150P
-	-	-	-	GND (Bank 7)	-	-
B14	BK7_IO7	-	220N	BK7_IO7	-	150N
C14	BK7_IO8	-	221P	BK7_IO8	-	151P
D14	BK7_IO9	-	221N	BK7_IO9	-	151N
E14	BK7_IO10	-	222P	BK7_IO10	-	152P
-	GND (Bank 7)	-	-	-	-	-
F14	BK7_IO11	-	222N	BK7_IO11	-	152N
C13	BK7_IO12	-	223P	BK7_IO12	-	153P
D13	BK7_IO13	-	223N	BK7_IO13	-	153N
B13	BK7_IO14	-	224P	BK7_IO14	-	154P
-	-	-	-	GND (Bank 7)	-	-
A13	BK7_IO15	-	224N	BK7_IO15	-	154N
F13	BK7_IO16	-	225P	BK7_IO16	-	155P
G13	BK7_IO17	-	225N	BK7_IO17	-	155N
A12	BK7_IO18	-	226P	BK7_IO18	-	156P
-	GND (Bank 7)	-	-	-	-	-
B12	BK7_IO19	-	226N	BK7_IO19	-	156N
C12	BK7_IO20	-	227P	NC	-	-
D12	BK7_IO21	-	227N	NC	-	-
A11	BK7_IO22	-	228P	NC	-	-
B11	BK7_IO23	-	228N	NC	-	-
E12	BK7_IO24	-	229P	NC	-	-
F12	BK7_IO25	-	229N	NC	-	-
C11	BK7_IO26	-	230P	NC	-	-
-	GND (Bank 7)	-	-	-	-	-
D11	BK7_IO27	-	230N	NC	-	-
E11	BK7_IO28	-	231P	NC	-	-
F11	BK7_IO29	-	231N	NC	-	-
B10	BK7_IO30	-	232P	NC	-	-
A10	BK7_IO31	-	232N	NC	-	-
D10	BK7_IO32	-	233P	NC	-	-
E10	BK7_IO33	-	233N	NC	-	-
A9	BK7_IO34	-	234P	NC	-	-
-	GND (Bank 7)	-	-	-	-	-
B9	BK7_IO35	-	234N	NC	-	-

ispXPGA Logic Signal Connections: 900-Ball fpBGA (Cont.)

900 fpBGA Ball	LFX1200			LFX500		
	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]	Signal Name	Second Function	LVDS Pair/ sysHSI Reserved[1]
F10	BK7_IO36	-	235P	NC	-	-
G10	BK7_IO37	-	235N	NC	-	-
A8	BK7_IO38	-	236P	NC	-	-
B8	BK7_IO39	-	236N	NC	-	-
D9	BK7_IO40	-	237P	BK7_IO22	-	158P
-	-	-	-	GND (Bank 7)	-	-
E9	BK7_IO41	-	237N	BK7_IO23	-	158N
A7	BK7_IO42	-	238P	BK7_IO24	-	159P
-	GND (Bank 7)	-	-		-	-
B7	BK7_IO43	-	238N	BK7_IO25	-	159N
C8	BK7_IO44	-	239P	BK7_IO26	-	160P
D8	BK7_IO45	-	239N	BK7_IO27	-	160N
A6	BK7_IO46	-	240P	BK7_IO21	-	157N
B6	BK7_IO47	VREF7	240N	BK7_IO20	VREF7	157P
E8	BK7_IO48	-	241P	BK7_IO28	-	161P
F8	BK7_IO49	-	241N	BK7_IO29	-	161N
C7	BK7_IO50	-	242P	BK7_IO30	-	162P
-	GND (Bank 7)	-	-	GND (Bank 7)	-	-
D7	BK7_IO51	-	242N	BK7_IO31	-	162N
E7	BK7_IO52	-	243P	BK7_IO32	-	163P
F7	BK7_IO53	-	243N	BK7_IO33	-	163N
A5	BK7_IO54	-	244P	BK7_IO34	-	164P
B5	BK7_IO55	-	244N	BK7_IO35	-	164N
C6	BK7_IO56	-	245P	BK7_IO36	-	165P
D6	BK7_IO57	-	245N	BK7_IO37	-	165N
D5	BK7_IO58	-	246P	BK7_IO38	-	166P
-	GND (Bank 7)	-	-	GND (Bank 7)	-	-
C5	BK7_IO59	-	246N	BK7_IO39	-	166N
B4	BK7_IO60	-	247P	BK7_IO40	-	167P
A4	BK7_IO61	-	247N	BK7_IO41	-	167N
A3	TDO	-	-	TDO	-	-
B3	VCCJ	-	-	VCCJ	-	-
C4	TDI	-	-	TDI	-	-

1. If a sysHSI Block is used, the indicated sysHSI reserved pins are unavailable for general purpose I/O use.

"E-Series" Commercial (Cont.)

Part Number	Gates	Voltage	Speed Grade	Package	Balls
LFX500EC-03F900C	476K	1.8	-3	fpBGA	900
LFX1200EB-05F900C[2]	1.25M	2.5/3.3	-5	fpBGA	900
LFX1200EB-04F900C[2]	1.25M	2.5/3.3	-4	fpBGA	900
LFX1200EB-03F900C[2]	1.25M	2.5/3.3	-3	fpBGA	900
LFX1200EC-04F900C[2]	1.25M	1.8	-4	fpBGA	900
LFX1200EC-03F900C[2]	1.25M	1.8	-3	fpBGA	900
LFX1200EB-05FE680C[2]	1.25M	2.5/3.3	-5	fpSBGA	680
LFX1200EB-04FE680C[2]	1.25M	2.5/3.3	-4	fpSBGA	680
LFX1200EB-03FE680C[2]	1.25M	2.5/3.3	-3	fpSBGA	680
LFX1200EC-04FE680C[2]	1.25M	1.8	-4	fpSBGA	680
LFX1200EC-03FE680C[2]	1.25M	1.8	-3	fpSBGA	680

1. FH516 package was converted to F516 via PCN #09A-08.
2. Discontinued via PCN #03A-10.

"E-Series" Industrial

Part Number	Gates	Voltage	Speed Grade	Package	Balls
LFX125EB-04F256I	139K	2.5/3.3	-4	fpBGA	256
LFX125EB-03F256I	139K	2.5/3.3	-3	fpBGA	256
LFX125EC-03F256I	139K	1.8	-3	fpBGA	256
LFX125EB-04F516I	139K	2.5/3.3	-4	fpBGA	516
LFX125EB-03F516I	139K	2.5/3.3	-3	fpBGA	516
LFX125EC-03F516I	139K	1.8	-3	fpBGA	516
LFX125EB-04FH516I[1]	139K	2.5/3.3	-4	fpBGA	516
LFX125EB-03FH516I[1]	139K	2.5/3.3	-3	fpBGA	516
LFX125EC-03FH516I[1]	139K	1.8	-3	fpBGA	516
LFX200EB-04F256I	210K	2.5/3.3	-4	fpBGA	256
LFX200EB-03F256I	210K	2.5/3.3	-3	fpBGA	256
LFX200EC-03F256I	210K	1.8	-3	fpBGA	256
LFX200EB-04F516I	210K	2.5/3.3	-4	fpBGA	516
LFX200EB-03F516I	210K	2.5/3.3	-3	fpBGA	516
LFX200EC-03F516I	210K	1.8	-3	fpBGA	516
LFX200EB-04FH516I[1]	210K	2.5/3.3	-4	fpBGA	516
LFX200EB-03FH516I[1]	210K	2.5/3.3	-3	fpBGA	516
LFX200EC-03FH516I[1]	210K	1.8	-3	fpBGA	516
LFX500EB-04F516I	476K	2.5/3.3	-4	fpBGA	516
LFX500EB-03F516I	476K	2.5/3.3	-3	fpBGA	516
LFX500EC-03F516I	476K	1.8	-3	fpBGA	516
LFX500EB-04FH516I[1]	476K	2.5/3.3	-4	fpBGA	516
LFX500EB-03FH516I[1]	476K	2.5/3.3	-3	fpBGA	516
LFX500EC-03FH516I[1]	476K	1.8	-3	fpBGA	516
LFX500EB-04F900I	476K	2.5/3.3	-4	fpBGA	900
LFX500EB-03F900I	476K	2.5/3.3	-3	fpBGA	900
LFX500EC-03F900I	476K	1.8	-3	fpBGA	900